

# ABSTRACT

5 A chemical amplification positive resist composition  
comprising a polymeric mixture of a polyhydroxystyrene  
derivative having a Mw of 1000-500,000 and a copolymer of  
hydroxystyrene and (meth)acrylate having a Mw of 1000-  
500,000, as a base resin, has improved dry etching  
resistance, high sensitivity, high resolution, and process  
10 adaptability, and is suppressed in the slimming of pattern  
films after development with aqueous base.